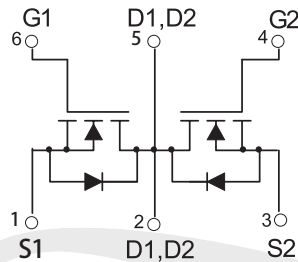
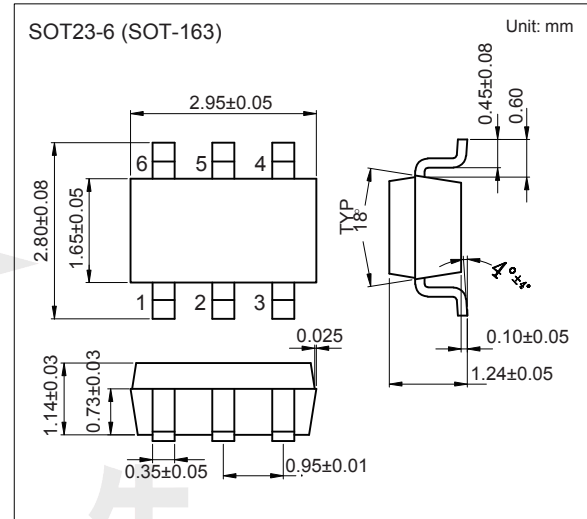


Dual N-Channel MOSFET XJ8205S

■ Features

- $V_{DS} = 20V$
- $I_D = 6A$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 25m\Omega$ ($V_{GS} = 4.5V$)
- $R_{DS(ON)} < 32m\Omega$ ($V_{GS} = 2.5V$)
- Battery Protection
- Load Switch
- Power Management



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	6	A
Pulsed Drain Current	I_{DM}	25	
Power Dissipation	P_D	350	mW
Thermal Resistance. Junction- to-Ambient	R_{thJA}	357	$^\circ C/W$
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	260	$^\circ C$
Junction Temperature	T_J	150	
Storage Temperature	T_{STG}	-55 to 150	

Dual N-Channel MOSFET XJ8205S

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250μA, V _{GS} =0V	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =18V, V _{GS} =0V			1	μA
Gate-Body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =250μA	0.5		0.9	V
Static Drain-Source On-Resistance	R _{Ds(on)}	V _{GS} =4.5V, I _D =6A			25	mΩ
		V _{GS} =2.5V, I _D =5A			32	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =4.5A		10		S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =8V, f=1MHz		800		pF
Output Capacitance	C _{oss}			155		
Reverse Transfer Capacitance	C _{rss}			125		
Total Gate Charge	Q _g	V _{DS} =10V, V _{GS} =4.5V, I _D =4A		11		nC
Gate Source Charge	Q _{gs}			2.3		
Gate Drain Charge	Q _{gd}			2.5		
Turn-On DelayTime	t _{d(on)}	V _{DD} =10V, V _{GS} =4V, I _D =1A, R _{GEN} =10Ω		18		ns
Turn-On Rise Time	t _r			5		
Turn-Off DelayTime	t _{d(off)}			43		
Turn-Off Fall Time	t _f			20		
Diode Forward Voltage	V _{SD}	I _S =1.25A, V _{GS} =0V			1.2	V

Dual N-Channel MOSFET XJ8205S

Typical Characteristics

